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APPLICANTS

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YES 6/13/2006

**** CONTINUING DATA *******

This application is a DIV of 10/187,269 07/02/2002 PAT 6,734,549

**** FOREIGN APPLICATIONS *******

JAPAN 2001-201950 07/03/2001

YES 6/13/2006

IF REQUIRED, FOREIGN FILING LICENSE GRANTED

** 06/28/2004

Foreign Priority claimed	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no	6/13/06	STATE OR COUNTRY	SHEETS DRAWING	TOTAL CLAIMS	INDEPENDENT CLAIMS
35 USC 119 (a-d) conditions met	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no	<input type="checkbox"/> Met after Allowance	JAPAN	25	12	5
Verified and Acknowledged	<input type="checkbox"/>	Examiner's Signature _____ Initials _____				

ADDRESS

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TITLE

Semiconductor wiring substrate, semiconductor device, method for testing semiconductor device, and method for mounting semiconductor device

FILING FEE RECEIVED 942	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:	<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees (Filing) <input type="checkbox"/> 1.17 Fees (Processing Ext. of time) <input type="checkbox"/> 1.18 Fees (Issue) <input type="checkbox"/> Other _____ <input type="checkbox"/> Credit
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